Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

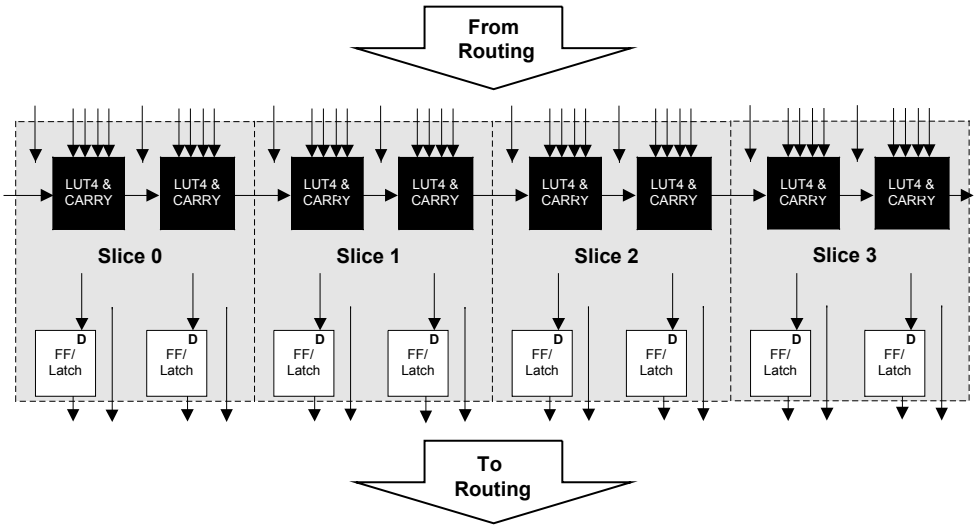
Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	10200
Total RAM Bits	282624
Number of I/O	195
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfecp10e-3f256i

PFU and PFF Blocks

The core of the LatticeECP/EC devices consists of PFU and PFF blocks. The PFUs can be programmed to perform Logic, Arithmetic, Distributed RAM and Distributed ROM functions. PFF blocks can be programmed to perform Logic, Arithmetic and ROM functions. Except where necessary, the remainder of the data sheet will use the term PFU to refer to both PFU and PFF blocks.

Each PFU block consists of four interconnected slices, numbered 0-3 as shown in Figure 2-3. All the interconnections to and from PFU blocks are from routing. There are 53 inputs and 25 outputs associated with each PFU block.

Figure 2-3. PFU Diagram



Slice

Each slice contains two LUT4 lookup tables feeding two registers (programmed to be in FF or Latch mode), and some associated logic that allows the LUTs to be combined to perform functions such as LUT5, LUT6, LUT7 and LUT8. There is control logic to perform set/reset functions (programmable as synchronous/asynchronous), clock select, chip-select and wider RAM/ROM functions. Figure 2-4 shows an overview of the internal logic of the slice. The registers in the slice can be configured for positive/negative and edge/level clocks.

There are 14 input signals: 13 signals from routing and one from the carry-chain (from adjacent slice or PFU). There are 7 outputs: 6 to routing and one to carry-chain (to adjacent PFU). Table 2-1 lists the signals associated with each slice.

Routing

There are many resources provided in the LatticeECP/EC devices to route signals individually or as busses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with x1 (spans two PFU), x2 (spans three PFU) and x6 (spans seven PFU). The x1 and x2 connections provide fast and efficient connections in horizontal and vertical directions. The x2 and x6 resources are buffered, the routing of both short and long connections between PFUs.

The ispLEVER design tool suite takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

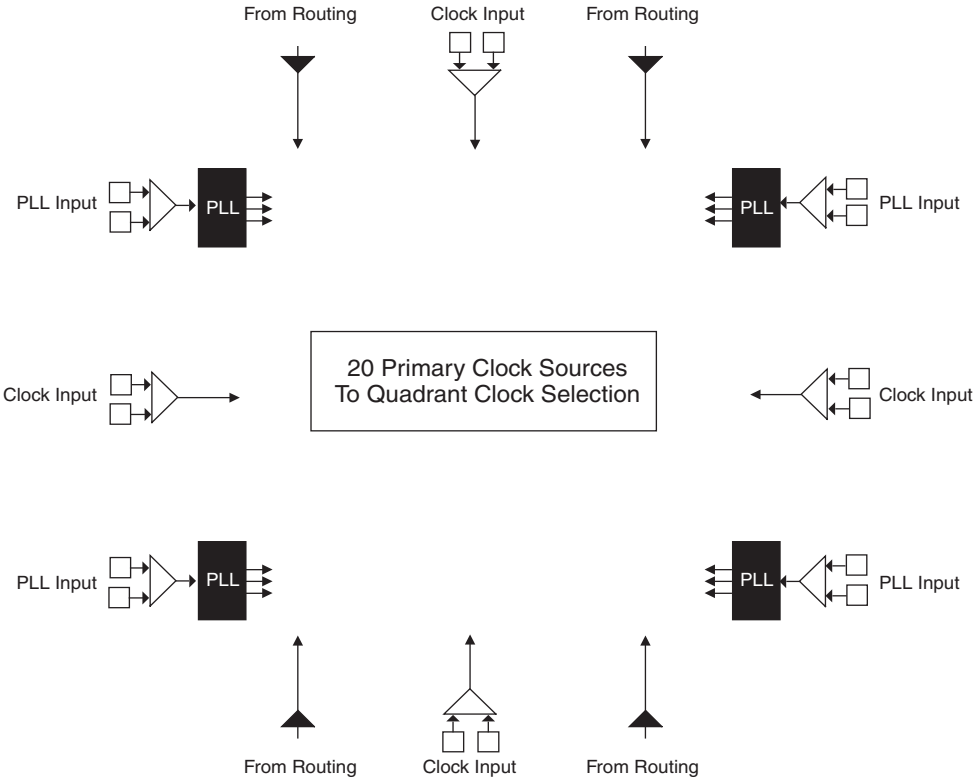
Clock Distribution Network

The clock inputs are selected from external I/O, the sysCLOCK™ PLLs or routing. These clock inputs are fed through the chip via a clock distribution system.

Primary Clock Sources

LatticeECP/EC devices derive clocks from three primary sources: PLL outputs, dedicated clock inputs and routing. LatticeECP/EC devices have two to four sysCLOCK PLLs, located on the left and right sides of the device. There are four dedicated clock inputs, one on each side of the device. Figure 2-6 shows the 20 primary clock sources.

Figure 2-6. Primary Clock Sources



Note: Smaller devices have two PLLs.

Signed and Unsigned with Different Widths

The DSP block supports different widths of signed and unsigned multipliers besides x9, x18 and x36 widths. For unsigned operands, unused upper data bits should be filled to create a valid x9, x18 or x36 operand. For signed two's complement operands, sign extension of the most significant bit should be performed until x9, x18 or x36 width is reached. Table 2-8 provides an example of this.

Table 2-8. An Example of Sign Extension

Number	Unsigned	Unsigned 9-bit	Unsigned 18-bit	Signed	Two's Complement Signed 9-Bits	Two's Complement Signed 18-bits
+5	0101	000000101	000000000000000101	0101	000000101	000000000000000101
-6	0110	000000110	000000000000000110	1010	111111010	111111111111111010

OVERFLOW Flag from MAC

The sysDSP block provides an overflow output to indicate that the accumulator has overflowed. When two unsigned numbers are added and the result is a smaller number then accumulator roll over is said to occur and overflow signal is indicated. When two positive numbers are added with a negative sum and when two negative numbers are added with a positive sum, then the accumulator "roll-over" is said to have occurred and an overflow signal is indicated. Note when overflow occurs the overflow flag is present for only one cycle. By counting these overflow pulses in FPGA logic, larger accumulators can be constructed. The conditions overflow signals for signed and unsigned operands are listed in Figure 2-23.

Figure 2-23. Accumulator Overflow/Underflow Conditions

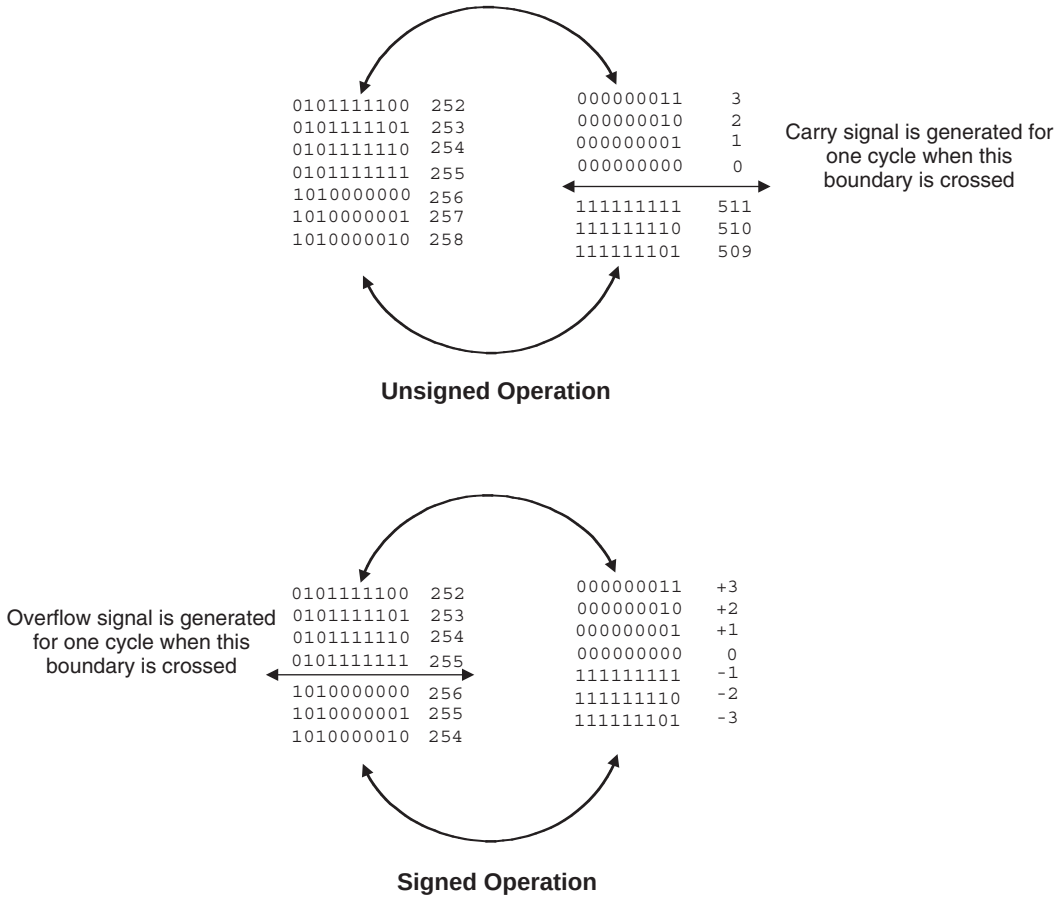
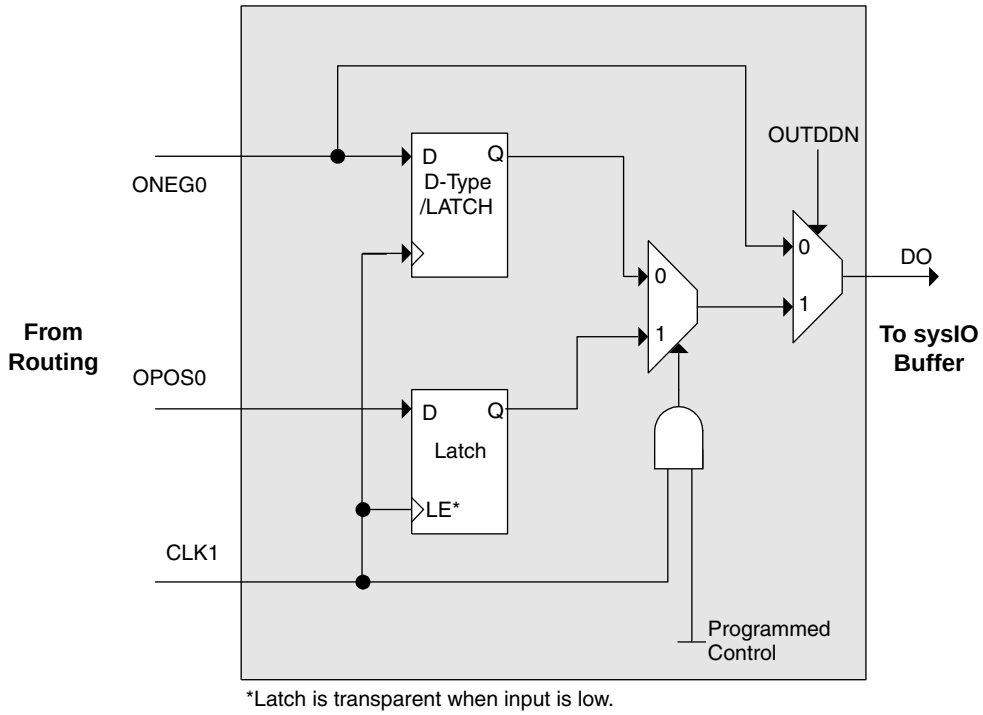
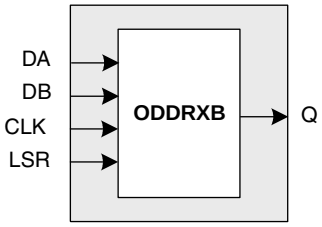


Figure 2-29. Output Register Block



*Latch is transparent when input is low.

Figure 2-30. ODDRXB Primitive



Tristate Register Block

The tristate register block provides the ability to register tri-state control signals from the core of the device before they are passed to the sysI/O buffers. The block contains a register for SDR operation and an additional latch for DDR operation. Figure 2-31 shows the diagram of the Tristate Register Block.

In SDR mode, ONEG1 feeds one of the flip-flops that then feeds the output. The flip-flop can be configured a D-type or latch. In DDR mode, ONEG1 is fed into one register on the positive edge of the clock and OPOS1 is latched. A multiplexer running off the same clock selects the correct register for feeding to the output (D0).

sysI/O Recommended Operating Conditions

Standard	V_{CCIO}			V_{REF} (V)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
LVCMOS 3.3	3.135	3.3	3.465	—	—	—
LVCMOS 2.5	2.375	2.5	2.625	—	—	—
LVCMOS 1.8	1.71	1.8	1.89	—	—	—
LVCMOS 1.5	1.425	1.5	1.575	—	—	—
LVCMOS 1.2	1.14	1.2	1.26	—	—	—
LVTTL	3.135	3.3	3.465	—	—	—
PCI	3.135	3.3	3.465	—	—	—
SSTL18 Class I	1.71	1.8	1.89	0.833	0.90	0.969
SSTL2 Class I, II	2.375	2.5	2.625	1.15	1.25	1.35
SSTL3 Class I, II	3.135	3.3	3.465	1.3	1.5	1.7
HSTL15 Class I	1.425	1.5	1.575	0.68	0.75	0.9
HSTL15 Class III	1.425	1.5	1.575	—	0.9	—
HSTL 18 Class I, II	1.71	1.8	1.89	—	0.9	—
HSTL 18 Class III	1.71	1.8	1.89	—	1.08	—
LVDS	2.375	2.5	2.625	—	—	—
LVPECL[1]	3.135	3.3	3.465	—	—	—
BLVDS[1]	2.375	2.5	2.625	—	—	—
RSDS[1]	2.375	2.5	2.625	—	—	—

1. Outputs are implemented with the addition of external resistors. V_{CCIO} applies to outputs only.

RSDS

The LatticeECP/EC devices support differential RSDS standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The RSDS input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Use LVDS25E mode with suggested resistors for RSDS operation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

Figure 3-4. RSDS (Reduced Swing Differential Standard)

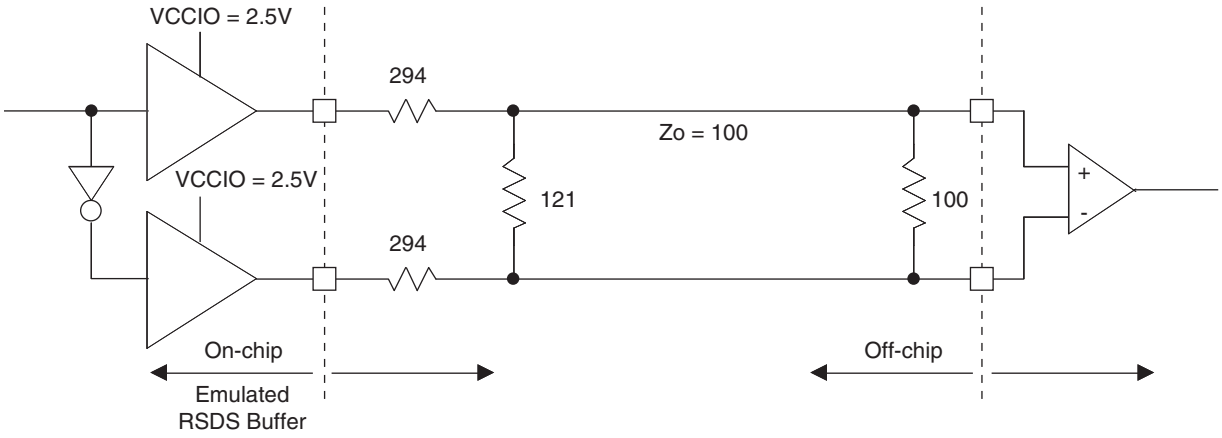


Table 3-4. RSDS DC Conditions

Parameter	Description	Typical	Units
Z_{OUT}	Output impedance	20	ohm
R_S	Driver series resistor	294	ohm
R_P	Driver parallel resistor	121	ohm
R_T	Receiver termination	100	ohm
V_{OH}	Output high voltage	1.35	V
V_{OL}	Output low voltage	1.15	V
V_{OD}	Output differential voltage	0.20	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	101.5	ohm
I_{DC}	DC output current	3.66	mA

LatticeECP/EC Internal Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
PFU/PFF Logic Mode Timing								
t_{LUT4_PFU}	LUT4 Delay (A to D Inputs to F Output)	—	0.25	—	0.31	—	0.36	ns
t_{LUT6_PFU}	LUT6 Delay (A to D Inputs to OFX Output)	—	0.40	—	0.48	—	0.56	ns
t_{LSR_PFU}	Set/Reset to Output of PFU	—	0.81	—	0.98	—	1.14	ns
t_{SUM_PFU}	Clock to Mux (M0,M1) Input Setup Time	0.12	—	0.14	—	0.16	—	ns
t_{HM_PFU}	Clock to Mux (M0,M1) Input Hold Time	-0.05	—	-0.06	—	-0.06	—	ns
t_{SUD_PFU}	Clock to D Input Setup Time	0.12	—	0.14	—	0.16	—	ns
t_{HD_PFU}	Clock to D Input Hold time	-0.03	—	-0.03	—	-0.04	—	ns
t_{CK2Q_PFU}	Clock to Q Delay, D-type Register Configuration	—	0.36	—	0.44	—	0.51	ns
t_{LE2Q_PFU}	Clock to Q Delay Latch Configuration	—	0.48	—	0.58	—	0.68	ns
t_{LD2Q_PFU}	D to Q Throughput Delay when Latch is Enabled	—	0.50	—	0.60	—	0.69	ns
PFU Dual Port Memory Mode Timing								
t_{CORAM_PFU}	Clock to Output	—	0.36	—	0.44	—	0.51	ns
t_{SUDATA_PFU}	Data Setup Time	-0.20	—	-0.24	—	-0.28	—	ns
t_{HDATA_PFU}	Data Hold Time	0.26	—	0.31	—	0.36	—	ns
t_{SUADDR_PFU}	Address Setup Time	-0.51	—	-0.62	—	-0.72	—	ns
t_{HADDR_PFU}	Address Hold Time	0.64	—	0.77	—	0.90	—	ns
t_{SUWREN_PFU}	Write/Read Enable Setup Time	-0.24	—	-0.29	—	-0.34	—	ns
t_{HWREN_PFU}	Write/Read Enable Hold Time	0.30	—	0.36	—	0.42	—	ns
PIC Timing								
PIO Input/Output Buffer Timing								
t_{IN_PIO}	Input Buffer Delay	—	0.56	—	0.67	—	0.78	ns
t_{OUT_PIO}	Output Buffer Delay	—	1.92	—	2.31	—	2.69	ns
IOLOGIC Input/Output Timing								
t_{SUI_PIO}	Input Register Setup Time (Data Before Clock)	0.90	—	1.08	—	1.26	—	ns
t_{HI_PIO}	Input Register Hold Time (Data after Clock)	0.62	—	0.74	—	0.87	—	ns
t_{COO_PIO}	Output Register Clock to Output Delay	—	0.33	—	0.40	—	0.46	ns
t_{SUCE_PIO}	Input Register Clock Enable Setup Time	-0.10	—	-0.12	—	-0.14	—	ns
t_{HCE_PIO}	Input Register Clock Enable Hold Time	0.12	—	0.14	—	0.17	—	ns
t_{SULSR_PIO}	Set/Reset Setup Time	0.18	—	0.21	—	0.25	—	ns
t_{HLSR_PIO}	Set/Reset Hold Time	-0.15	—	-0.18	—	-0.21	—	ns
EBR Timing								
t_{CO_EBR}	Clock to Output from Address or Data	—	3.64	—	4.37	—	5.10	ns
t_{COO_EBR}	Clock to Output from EBR output Register	—	0.74	—	0.88	—	1.03	ns
t_{SUDATA_EBR}	Setup Data to EBR Memory	-0.29	—	-0.35	—	-0.41	—	ns
t_{HDATA_EBR}	Hold Data to EBR Memory	0.37	—	0.44	—	0.52	—	ns
t_{SUADDR_EBR}	Setup Address to EBR Memory	-0.29	—	-0.35	—	-0.41	—	ns
t_{HADDR_EBR}	Hold Address to EBR Memory	0.37	—	0.45	—	0.52	—	ns
t_{SUWREN_EBR}	Setup Write/Read Enable to EBR Memory	-0.18	—	-0.22	—	-0.26	—	ns
t_{HWREN_EBR}	Hold Write/Read Enable to EBR Memory	0.23	—	0.28	—	0.33	—	ns

LatticeECP/EC Family Timing Adders[1, 2, 3] (Continued)

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
HSTL15_II	HSTL_15 class II	0.10	0.12	0.14	ns
HSTL15_III	HSTL_15 class III	0.10	0.12	0.14	ns
HSTL15D_I	Differential HSTL 15 class I	0.08	0.10	0.11	ns
HSTL15D_III	Differential HSTL 15 class III	0.10	0.12	0.14	ns
SSTL33_I	SSTL_3 class I	-0.05	-0.06	-0.07	ns
SSTL33_II	SSTL_3 class II	0.40	0.48	0.56	ns
SSTL33D_I	Differential SSTL_3 class I	-0.05	-0.06	-0.07	ns
SSTL33D_II	Differential SSTL_3 class II	0.40	0.48	0.56	ns
SSTL25_I	SSTL_2 class I	0.05	0.07	0.08	ns
SSTL25_II	SSTL_2 class II	0.25	0.30	0.35	ns
SSTL25D_I	Differential SSTL_2 class I	0.05	0.07	0.08	ns
SSTL25D_II	Differential SSTL_2 class II	0.25	0.30	0.35	ns
SSTL18_I	SSTL_1.8 class I	0.01	0.01	0.01	ns
SSTL18D_I	Differential SSTL_1.8 class I	0.01	0.01	0.01	ns
LVTTL33_4mA	LVTTL 4mA drive	0.09	0.11	0.13	ns
LVTTL33_8mA	LVTTL 8mA drive	0.07	0.08	0.09	ns
LVTTL33_12mA	LVTTL 12mA drive	-0.03	-0.04	-0.05	ns
LVTTL33_16mA	LVTTL 16mA drive	0.36	0.43	0.51	ns
LVTTL33_20mA	LVTTL 20mA drive	0.28	0.33	0.39	ns
LVCMOS33_4mA	LVCMOS 3.3 4mA drive	0.09	0.11	0.13	ns
LVCMOS33_8mA	LVCMOS 3.3 8mA drive	0.07	0.08	0.09	ns
LVCMOS33_12mA	LVCMOS 3.3 12mA drive	-0.03	-0.04	-0.05	ns
LVCMOS33_16mA	LVCMOS 3.3 16mA drive	0.36	0.43	0.51	ns
LVCMOS33_20mA	LVCMOS 3.3 20mA drive	0.28	0.33	0.39	ns
LVCMOS25_4mA	LVCMOS 2.5 4mA drive	0.18	0.21	0.25	ns
LVCMOS25_8mA	LVCMOS 2.5 8mA drive	0.10	0.12	0.14	ns
LVCMOS25_12mA	LVCMOS 2.5 12mA drive	0.00	0.00	0.00	ns
LVCMOS25_16mA	LVCMOS 2.5 16mA drive	0.22	0.26	0.31	ns
LVCMOS25_20mA	LVCMOS 2.5 20mA drive	0.14	0.16	0.19	ns
LVCMOS18_4mA	LVCMOS 1.8 4mA drive	0.15	0.18	0.21	ns
LVCMOS18_8mA	LVCMOS 1.8 8mA drive	0.06	0.08	0.09	ns
LVCMOS18_12mA	LVCMOS 1.8 12mA drive	0.01	0.01	0.01	ns
LVCMOS18_16mA	LVCMOS 1.8 16mA drive	0.16	0.19	0.22	ns
LVCMOS15_4mA	LVCMOS 1.5 4mA drive	0.26	0.31	0.36	ns
LVCMOS15_8mA	LVCMOS 1.5 8mA drive	0.04	0.04	0.05	ns
LVCMOS12_2mA	LVCMOS 1.2 2mA drive	0.36	0.43	0.50	ns
LVCMOS12_6mA	LVCMOS 1.2 6mA drive	0.08	0.10	0.11	ns
LVCMOS12_4mA	LVCMOS 1.2 4mA drive	0.36	0.43	0.50	ns
PCI33	PCI33	1.05	1.26	1.46	ns

1. Timing adders are characterized but not tested on every device.
2. LVCMOS timing measured with the load specified in Switching Test Conditions table of this document.
3. All other standards according to the appropriate specification.

Timing v.G 0.30

LFEC1, LFEC3 Logic Signal Connections: 100 TQFP

Pin Number	LFEC1				LFEC3			
	Pin Function	Bank	LVDS	Dual Function	Pin Function	Bank	LVDS	Dual Function
1*	GND0 GND7	-			GND0 GND7	-		
2	VCCIO7	7			VCCIO7	7		
3	PL2A	7	T	VREF2_7	PL2A	7	T	VREF2_7
4	PL2B	7	C	VREF1_7	PL2B	7	C	VREF1_7
5	PL3A	7	T		PL7A	7	T	
6	PL3B	7	C		PL7B	7	C	
7	PL4A	7	T		PL8A	7	T	
8	PL4B	7	C		PL8B	7	C	
9	PL5A	7	T	PCLKT7_0	PL9A	7	T	PCLKT7_0
10	PL5B	7	C	PCLKC7_0	PL9B	7	C	PCLKC7_0
11	XRES	6			XRES	6		
12	VCC	-			VCC	-		
13	TCK	6			TCK	6		
14	GND	-			GND	-		
15	TDI	6			TDI	6		
16	TMS	6			TMS	6		
17	TDO	6			TDO	6		
18	VCCJ	6			VCCJ	6		
19	PL7A	6	T	LLM0_PLLT_IN_A	PL11A	6	T	LUM0_PLLT_IN_A
20	PL7B	6	C	LLM0_PLLC_IN_A	PL11B	6	C	LUM0_PLLC_IN_A
21	PL8A	6	T	LLM0_PLLT_FB_A	PL12A	6	T	LUM0_PLLT_FB_A
22	PL8B	6	C	LLM0_PLLC_FB_A	PL12B	6	C	LUM0_PLLC_FB_A
23	PL14A	6		VREF1_6	PL18A	6		VREF1_6
24	VCCIO6	6			VCCIO6	6		
25*	GND5 GND6	-			GND5 GND6	-		
26	VCCIO5	5			VCCIO5	5		
27	PB2A	5	T		PB10A	5	T	
28	PB2B	5	C		PB10B	5	C	
29	PB3A	5	T		PB11A	5	T	
30	PB3B	5	C		PB11B	5	C	
31	PB6A	5		BDQS6	PB14A	5		BDQS14
32	PB8A	5	T	VREF2_5	PB16A	5	T	VREF2_5
33	PB8B	5	C	VREF1_5	PB16B	5	C	VREF1_5
34	PB9A	5	T	PCLKT5_0	PB17A	5	T	PCLKT5_0
35	GND5	5			GND5	5		
36	PB9B	5	C	PCLKC5_0	PB17B	5	C	PCLKC5_0
37	VCCAUX	-			VCCAUX	-		
38	VCCIO4	4			VCCIO4	4		
39	PB10A	4	T	WRITEN	PB18A	4	T	WRITEN
40	PB10B	4	C	CS1N	PB18B	4	C	CS1N

LFECP/EC6, LFECP/EC10 Logic Signal Connections: 208 PQFP

Pin Number	LFECP6/LFEC6				LFECP10/LFEC10			
	Pin Function	Bank	LVDS	Dual Function	Pin Function	Bank	LVDS	Dual Function
1*	GND0 GND7	-			GND0 GND7	-		
2	VCCIO7	7			VCCIO7	7		
3	PL2A	7	T	VREF2_7	PL2A	7	T	VREF2_7
4	PL2B	7	C	VREF1_7	PL2B	7	C	VREF1_7
5	NC	-			VCC	-		
6	NC	-			GND	-		
7	PL3B	7			PL12B	7		
8	PL4A	7	T		PL13A	7	T	
9	PL4B	7	C		PL13B	7	C	
10	PL5A	7	T		PL14A	7	T	
11	PL5B	7	C		PL14B	7	C	
12	PL6A	7	T	LDQS6	PL15A	7	T	LDQS15
13	VCCIO7	7			VCCIO7	7		
14	PL6B	7	C		PL15B	7	C	
15	PL7A	7	T		PL16A	7	T	
16	PL7B	7	C		PL16B	7	C	
17	PL8A	7	T		PL17A	7	T	
18	GND7	7			GND7	7		
19	PL8B	7	C		PL17B	7	C	
20	PL9A	7	T	PCLKT7_0	PL18A	7	T	PCLKT7_0
21	PL9B	7	C	PCLKC7_0	PL18B	7	C	PCLKC7_0
22	VCCAUX	-			VCCAUX	-		
23	XRES	6			XRES	6		
24	VCC	-			VCC	-		
25	GND	-			GND	-		
26	VCC	-			VCC	-		
27	TCK	6			TCK	6		
28	GND	-			GND	-		
29	TDI	6			TDI	6		
30	TMS	6			TMS	6		
31	TDO	6			TDO	6		
32	VCCJ	6			VCCJ	6		
33	PL20A	6	T	LLM0_PLLT_IN_A	PL29A	6	T	LLM0_PLLT_IN_A
34	PL20B	6	C	LLM0_PLLC_IN_A	PL29B	6	C	LLM0_PLLC_IN_A
35	PL21A	6	T	LLM0_PLLT_FB_A	PL30A	6	T	LLM0_PLLT_FB_A
36	PL21B	6	C	LLM0_PLLC_FB_A	PL30B	6	C	LLM0_PLLC_FB_A
37	VCCIO6	6			VCCIO6	6		
38	PL22A	6	T		PL31A	6	T	
39	PL22B	6	C		PL31B	6	C	
40	PL23A	6	T		PL32A	6	T	
41	GND6	6			GND6	6		
42	PL23B	6	C		PL32B	6	C	

LFEC3 and LFECP/EC6 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFEC3				LFECP6/LFEC6			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
E5	VCC	-			VCC	-		
E8	VCC	-			VCC	-		
M12	VCC	-			VCC	-		
M5	VCC	-			VCC	-		
M9	VCC	-			VCC	-		
B15	VCCAUX	-			VCCAUX	-		
R2	VCCAUX	-			VCCAUX	-		
F7	VCCIO0	0			VCCIO0	0		
F8	VCCIO0	0			VCCIO0	0		
F10	VCCIO1	1			VCCIO1	1		
F9	VCCIO1	1			VCCIO1	1		
G11	VCCIO2	2			VCCIO2	2		
H11	VCCIO2	2			VCCIO2	2		
J11	VCCIO3	3			VCCIO3	3		
K11	VCCIO3	3			VCCIO3	3		
L10	VCCIO4	4			VCCIO4	4		
L9	VCCIO4	4			VCCIO4	4		
L7	VCCIO5	5			VCCIO5	5		
L8	VCCIO5	5			VCCIO5	5		
J6	VCCIO6	6			VCCIO6	6		
K6	VCCIO6	6			VCCIO6	6		
G6	VCCIO7	7			VCCIO7	7		
H6	VCCIO7	7			VCCIO7	7		
F6	VCC	-			VCC	-		
F11	VCC	-			VCC	-		
L11	VCC	-			VCC	-		
L6	VCC	-			VCC	-		

LFECP/EC6, LFECP/EC10, LFECP/EC15 Logic Signal Connections: 484 fpBGA (Cont.)

LFECP6/LFEC6					LFECP10/LFEC10					LFECP/LFEC15				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
W17	NC	-			W17	NC	-			W17	PB46B	4	C	
AA20	NC	-			AA20	NC	-			AA20	PB47A	4	T	
Y19	NC	-			Y19	NC	-			Y19	PB47B	4	C	
Y18	NC	-			Y18	NC	-			Y18	PB48A	4	T	
W18	NC	-			W18	NC	-			W18	PB48B	4	C	
T17	NC	-			T17	NC	-			T17	PB49A	4	T	
U17	NC	-			U17	NC	-			U17	PB49B	4	C	
GND	GND4	4			GND	GND4	4			GND	GND4	4		
GND	GND3	3			GND	GND3	3			GND	GND3	3		
W20	PR27B	3	C	VREF2_3	W20	PR36B	3	C	VREF2_3	W20	PR44B	3	C	VREF2_3
Y20	PR27A	3	T	VREF1_3	Y20	PR36A	3	T	VREF1_3	Y20	PR44A	3	T	VREF1_3
AA21	PR26B	3	C		AA21	PR35B	3	C		AA21	PR43B	3	C	
AB21	PR26A	3	T		AB21	PR35A	3	T		AB21	PR43A	3	T	
W19	PR25B	3	C		W19	PR34B	3	C		W19	PR42B	3	C	
V19	PR25A	3	T		V19	PR34A	3	T		V19	PR42A	3	T	
Y21	PR24B	3	C		Y21	PR33B	3	C		Y21	PR41B	3	C	
AA22	PR24A	3	T	RDQS24	AA22	PR33A	3	T	RDQS33	AA22	PR41A	3	T	RDQS41
V20	PR23B	3	C	RLM0_PLLC_FB_A	V20	PR32B	3	C	RLM0_PLLC_FB_A	V20	PR40B	3	C	RLM0_PLLC_FB_A
GND	GND3	3			GND	GND3	3			GND	GND3	3		
U20	PR23A	3	T	RLM0_PLLT_FB_A	U20	PR32A	3	T	RLM0_PLLT_FB_A	U20	PR40A	3	T	RLM0_PLLT_FB_A
W21	PR22B	3	C	RLM0_PLLC_IN_A	W21	PR31B	3	C	RLM0_PLLC_IN_A	W21	PR39B	3	C	RLM0_PLLC_IN_A
Y22	PR22A	3	T	RLM0_PLLT_IN_A	Y22	PR31A	3	T	RLM0_PLLT_IN_A	Y22	PR39A	3	T	RLM0_PLLT_IN_A
V21	PR21B	3	C	DI/CSSPIN	V21	PR30B	3	C	DI/CSSPIN	V21	PR38B	3	C	DI/CSSPIN
W22	PR21A	3	T	DOUT/CSON	W22	PR30A	3	T	DOUT/CSON	W22	PR38A	3	T	DOUT/CSON
U21	PR20B	3	C	BUSY/SISPI	U21	PR29B	3	C	BUSY/SISPI	U21	PR37B	3	C	BUSY/SISPI
V22	PR20A	3	T	D7/SPID0	V22	PR29A	3	T	D7/SPID0	V22	PR37A	3	T	D7/SPID0
T19	CFG2	3			T19	CFG2	3			T19	CFG2	3		
U19	CFG1	3			U19	CFG1	3			U19	CFG1	3		
U18	CFG0	3			U18	CFG0	3			U18	CFG0	3		
V18	PROGRAMN	3			V18	PROGRAMN	3			V18	PROGRAMN	3		
T20	CCLK	3			T20	CCLK	3			T20	CCLK	3		
T21	INITN	3			T21	INITN	3			T21	INITN	3		
R20	DONE	3			R20	DONE	3			R20	DONE	3		
T18	NC	-			T18	NC	-			T18	NC	-		
R17	NC	-			R17	NC	-			R17	NC	-		
R19	NC	-			R19	NC	-			R19	NC	-		
R18	NC	-			R18	NC	-			R18	NC	-		
U22	NC	-			U22	NC	-			U22	PR35B	3	C	
GND	-	-			GND	-	-			GND	GND3	3		
T22	NC	-			T22	NC	-			T22	PR35A	3	T	
R21	NC	-			R21	NC	-			R21	PR34B	3	C	
R22	NC	-			R22	NC	-			R22	PR34A	3	T	
P20	NC	-			P20	NC	-			P20	PR33B	3	C	
N20	NC	-			N20	NC	-			N20	PR33A	3	T	
P19	NC	-			P19	NC	-			P19	PR32B	3	C	
P18	NC	-			P18	NC	-			P18	PR32A	3	T	
P21	PR18B	3	C		P21	PR27B	3	C		P21	PR31B	3	C	
GND	GND3	3			GND	GND3	3			GND	GND3	3		
P22	PR18A	3	T		P22	PR27A	3	T		P22	PR31A	3	T	
N21	PR17B	3	C		N21	PR26B	3	C		N21	PR30B	3	C	

LFECP/EC20 and LFECP/EC33 Logic Signal Connections: 484 fpBGA

LFECP20/LFEC20					LFECP/LFEC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
GND	GND7	7			GND	GND7	7		
D4	PL2A	7	T	VREF2_7	D4	PL2A	7	T	VREF2_7
E4	PL2B	7	C	VREF1_7	E4	PL2B	7	C	VREF1_7
GND	-	-			GND	GND7	7		
C3	PL3A	7	T		C3	PL10A	7	T	
B2	PL3B	7	C		B2	PL10B	7	C	
E5	PL4A	7	T		E5	PL11A	7	T	
F5	PL4B	7	C		F5	PL11B	7	C	
D3	PL5A	7	T		D3	PL12A	7	T	
C2	PL5B	7	C		C2	PL12B	7	C	
GND	-	-			GND	GND7	7		
F4	PL6A	7	T	LDQS6	F4	PL14A	7	T	LDQS14
G4	PL6B	7	C		G4	PL14B	7	C	
E3	PL7A	7	T		E3	PL15A	7	T	
D2	PL7B	7	C		D2	PL15B	7	C	
B1	PL8A	7	T	LUM0_PLLT_IN_A	B1	PL16A	7	T	LUM0_PLLT_IN_A
C1	PL8B	7	C	LUM0_PLLC_IN_A	C1	PL16B	7	C	LUM0_PLLC_IN_A
F3	PL9A	7	T	LUM0_PLLT_FB_A	F3	PL17A	7	T	LUM0_PLLT_FB_A
GND	GND7	7			GND	GND7	7		
E2	PL9B	7	C	LUM0_PLLC_FB_A	E2	PL17B	7	C	LUM0_PLLC_FB_A
GND	-	-			GND	GND7	7		
G5	PL11A	7	T		G5	PL23A	7	T	LDQS23
H6	PL11B	7	C		H6	PL23B	7	C	
G3	PL12A	7	T		G3	PL24A	7	T	
H4	PL12B	7	C		H4	PL24B	7	C	
J5	PL13A	7	T		J5	PL25A	7	T	
H5	PL13B	7	C		H5	PL25B	7	C	
F2	PL14A	7	T		F2	PL26A	7	T	
GND	GND7	7			GND	GND7	7		
F1	PL14B	7	C		F1	PL26B	7	C	
E1	PL15A	7	T		E1	PL27A	7	T	
D1	PL15B	7	C		D1	PL27B	7	C	
H3	PL16A	7	T		H3	PL28A	7	T	
G2	PL16B	7	C		G2	PL28B	7	C	
H2	PL17A	7	T		H2	PL29A	7	T	
G1	PL17B	7	C		G1	PL29B	7	C	
J4	PL18A	7	T		J4	PL30A	7	T	
GND	GND7	7			GND	GND7	7		
J3	PL18B	7	C		J3	PL30B	7	C	
J2	PL19A	7	T	LDQS19	J2	PL31A	7	T	LDQS31
H1	PL19B	7	C		H1	PL31B	7	C	
K4	PL20A	7	T		K4	PL32A	7	T	
K5	PL20B	7	C		K5	PL32B	7	C	

LFECP/EC20 and LFECP/EC33 Logic Signal Connections: 484 fpBGA (Cont.)

LFECP20/LFEC20					LFECP/LFEC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
K3	PL21A	7	T		K3	PL33A	7	T	
K2	PL21B	7	C		K2	PL33B	7	C	
J1	PL22A	7	T	PCLKT7_0	J1	PL34A	7	T	PCLKT7_0
GND	GND7	7			GND	GND7	7		
K1	PL22B	7	C	PCLKC7_0	K1	PL34B	7	C	PCLKC7_0
L3	XRES	6			L3	XRES	6		
L4	PL24A	6	T		L4	PL36A	6	T	
L5	PL24B	6	C		L5	PL36B	6	C	
L2	PL25A	6	T		L2	PL37A	6	T	
L1	PL25B	6	C		L1	PL37B	6	C	
M4	PL26A	6	T		M4	PL38A	6	T	
M5	PL26B	6	C		M5	PL38B	6	C	
M1	PL27A	6	T		M1	PL39A	6	T	
GND	GND6	6			GND	GND6	6		
M2	PL27B	6	C		M2	PL39B	6	C	
N3	PL28A	6	T	LDQS28	N3	PL40A	6	T	LDQS40
M3	PL28B	6	C		M3	PL40B	6	C	
N5	PL29A	6	T		N5	PL41A	6	T	
N4	PL29B	6	C		N4	PL41B	6	C	
N1	PL30A	6	T		N1	PL42A	6	T	
N2	PL30B	6	C		N2	PL42B	6	C	
P1	PL31A	6	T		P1	PL43A	6	T	
GND	GND6	6			GND	GND6	6		
P2	PL31B	6	C		P2	PL43B	6	C	
R6	PL32A	6	T		R6	PL44A	6	T	
P5	PL32B	6	C		P5	PL44B	6	C	
P3	PL33A	6	T		P3	PL45A	6	T	
P4	PL33B	6	C		P4	PL45B	6	C	
R1	PL34A	6	T		R1	PL46A	6	T	
R2	PL34B	6	C		R2	PL46B	6	C	
R5	PL35A	6	T		R5	PL47A	6	T	
GND	GND6	6			GND	GND6	6		
R4	PL35B	6	C		R4	PL47B	6	C	
T1	PL36A	6	T	LDQS36	T1	PL48A	6	T	LDQS48
T2	PL36B	6	C		T2	PL48B	6	C	
R3	PL37A	6	T		R3	PL49A	6	T	
T3	PL37B	6	C		T3	PL49B	6	C	
GND	GND6	6			GND	GND6	6		
T5	TCK	6			T5	TCK	6		
U5	TDI	6			U5	TDI	6		
T4	TMS	6			T4	TMS	6		
U1	TDO	6			U1	TDO	6		
U2	VCCJ	6			U2	VCCJ	6		
V1	PL41A	6	T	LLM0_PLLT_IN_A	V1	PL53A	6	T	LLM0_PLLT_IN_A

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following located on the Lattice website at www.latticesemi.com.

- Thermal Management document
- Technical Note TN1052 - Power Estimation and Management for LatticeECP/EC and LatticeXP Devices
- Power Calculator tool included with Lattice's ispLEVER design tool, or as a standalone download from www.latticesemi.com/software

LatticeECP Commercial

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFECP6E-3FN484C	224	-3	Lead-Free fpBGA	484	COM	6.1K
LFECP6E-4FN484C	224	-4	Lead-Free fpBGA	484	COM	6.1K
LFECP6E-5FN484C	224	-5	Lead-Free fpBGA	484	COM	6.1K
LFECP6E-3FN256C	195	-3	Lead-Free fpBGA	256	COM	6.1K
LFECP6E-4FN256C	195	-4	Lead-Free fpBGA	256	COM	6.1K
LFECP6E-5FN256C	195	-5	Lead-Free fpBGA	256	COM	6.1K
LFECP6E-3QN208C	147	-3	Lead-Free PQFP	208	COM	6.1K
LFECP6E-4QN208C	147	-4	Lead-Free PQFP	208	COM	6.1K
LFECP6E-5QN208C	147	-5	Lead-Free PQFP	208	COM	6.1K
LFECP6E-3TN144C	97	-3	Lead-Free TQFP	144	COM	6.1K
LFECP6E-4TN144C	97	-4	Lead-Free TQFP	144	COM	6.1K
LFECP6E-5TN144C	97	-5	Lead-Free TQFP	144	COM	6.1K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFECP10E-3FN484C	288	-3	Lead-Free fpBGA	484	COM	10.2K
LFECP10E-4FN484C	288	-4	Lead-Free fpBGA	484	COM	10.2K
LFECP10E-5FN484C	288	-5	Lead-Free fpBGA	484	COM	10.2K
LFECP10E-3FN256C	195	-3	Lead-Free fpBGA	256	COM	10.2K
LFECP10E-4FN256C	195	-4	Lead-Free fpBGA	256	COM	10.2K
LFECP10E-5FN256C	195	-5	Lead-Free fpBGA	256	COM	10.2K
LFECP10E-3QN208C	147	-3	Lead-Free PQFP	208	COM	10.2K
LFECP10E-4QN208C	147	-4	Lead-Free PQFP	208	COM	10.2K
LFECP10E-5QN208C	147	-5	Lead-Free PQFP	208	COM	10.2K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFECP15E-3FN484C	352	-3	Lead-Free fpBGA	484	COM	15.3K
LFECP15E-4FN484C	352	-4	Lead-Free fpBGA	484	COM	15.3K
LFECP15E-5FN484C	352	-5	Lead-Free fpBGA	484	COM	15.3K
LFECP15E-3FN256C	195	-3	Lead-Free fpBGA	256	COM	15.3K
LFECP15E-4FN256C	195	-4	Lead-Free fpBGA	256	COM	15.3K
LFECP15E-5FN256C	195	-5	Lead-Free fpBGA	256	COM	15.3K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFECP20E-3FN672C	400	-3	Lead-Free fpBGA	672	COM	19.7K
LFECP20E-4FN672C	400	-4	Lead-Free fpBGA	672	COM	19.7K
LFECP20E-5FN672C	400	-5	Lead-Free fpBGA	672	COM	19.7K
LFECP20E-3FN484C	400	-3	Lead-Free fpBGA	484	COM	19.7K
LFECP20E-4FN484C	400	-4	Lead-Free fpBGA	484	COM	19.7K
LFECP20E-5FN484C	400	-5	Lead-Free fpBGA	484	COM	19.7K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFECP33E-3FN672C	496	-3	Lead-Free fpBGA	672	COM	32.8K
LFECP33E-4FN672C	496	-4	Lead-Free fpBGA	672	COM	32.8K
LFECP33E-5FN672C	496	-5	Lead-Free fpBGA	672	COM	32.8K

LatticeECP Commercial (Continued)

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFECP33E-3FN484C	360	-3	Lead-Free fpBGA	484	COM	32.8K
LFECP33E-4FN484C	360	-4	Lead-Free fpBGA	484	COM	32.8K
LFECP33E-5FN484C	360	-5	Lead-Free fpBGA	484	COM	32.8K

LatticeEC Industrial

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC1E-3QN208I	112	-3	Lead-Free PQFP	208	IND	1.5K
LFEC1E-4QN208I	112	-4	Lead-Free PQFP	208	IND	1.5K
LFEC1E-3TN144I	97	-3	Lead-Free TQFP	144	IND	1.5K
LFEC1E-4TN144I	97	-4	Lead-Free TQFP	144	IND	1.5K
LFEC1E-3TN100I	67	-3	Lead-Free TQFP	100	IND	1.5K
LFEC1E-4TN100I	67	-4	Lead-Free TQFP	100	IND	1.5K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC3E-3FN256I	160	-3	Lead-Free fpBGA	256	IND	3.1K
LFEC3E-4FN256I	160	-4	Lead-Free fpBGA	256	IND	3.1K
LFEC3E-3QN208I	145	-3	Lead-Free PQFP	208	IND	3.1K
LFEC3E-4QN208I	145	-4	Lead-Free PQFP	208	IND	3.1K
LFEC3E-3TN144I	97	-3	Lead-Free TQFP	144	IND	3.1K
LFEC3E-4TN144I	97	-4	Lead-Free TQFP	144	IND	3.1K
LFEC3E-3TN100I	67	-3	Lead-Free TQFP	100	IND	3.1K
LFEC3E-4TN100I	67	-4	Lead-Free TQFP	100	IND	3.1K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC6E-3FN484I	224	-3	Lead-Free fpBGA	484	IND	6.1K
LFEC6E-4FN484I	224	-4	Lead-Free fpBGA	484	IND	6.1K
LFEC6E-3FN256I	195	-3	Lead-Free fpBGA	256	IND	6.1K
LFEC6E-4FN256I	195	-4	Lead-Free fpBGA	256	IND	6.1K
LFEC6E-3QN208I	147	-3	Lead-Free PQFP	208	IND	6.1K
LFEC6E-4QN208I	147	-4	Lead-Free PQFP	208	IND	6.1K
LFEC6E-3TN144I	97	-3	Lead-Free TQFP	144	IND	6.1K
LFEC6E-4TN144I	97	-4	Lead-Free TQFP	144	IND	6.1K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC10E-3FN484I	288	-3	Lead-Free fpBGA	484	IND	10.2K
LFEC10E-4FN484I	288	-4	Lead-Free fpBGA	484	IND	10.2K
LFEC10E-3FN256I	195	-3	Lead-Free fpBGA	256	IND	10.2K
LFEC10E-4FN256I	195	-4	Lead-Free fpBGA	256	IND	10.2K
LFEC10E-3QN208I	147	-3	Lead-Free PQFP	208	IND	10.2K
LFEC10E-4QN208I	147	-4	Lead-Free PQFP	208	IND	10.2K

LatticeECP/EC Family Data Sheet Supplemental Information

For Further Information

A variety of technical notes for the LatticeECP/EC family are available on the Lattice web site at www.latticesemi.com.

- LatticeECP/EC sysIO Usage Guide (TN1056)
- LatticeECP/EC sysCLOCK PLL Design and Usage Guide (TN1049)
- Memory Usage Guide for LatticeECP/EC Devices (TN1051)
- LatticeECP/EC DDR Usage Guide (TN1050)
- Power Estimation and Management for LatticeECP/EC and LatticeXP Devices (TN1052)
- LatticeECP-DSP sysDSP Usage Guide (TN1057)
- LatticeECP/EC sysCONFIG Usage Guide (TN1053)
- IEEE 1149.1 Boundary Scan Testability in Lattice Devices

For further information about interface standards refer to the following web sites:

- JEDEC Standards (LVTTL, LVCMOS, SSTL, HSTL): www.jedec.org
- PCI: ww.pcisig.com

LatticeECP/EC Family Data Sheet Revision History

Revision History

Date	Version	Section	Change Summary
June 2004	01.0	—	Initial release.
August 2004	01.1	Introduction	Added new device LFECP/LFEC33 in Table 1-1.
		Architecture	Added New device LFECP/LFEC33 in Tables 2-9, 2-10 and 2-11.
		DC & Switching Characteristics	Added New device LFECP/LFEC33 on Supply current (Standby) tables.
			Added New device LFECP/LFEC33 on Initialization Supply current tables.
		Ordering Information	Added 33K Logic Capacity Device in Part Number Description section.
			Added EC33, ECP33 device: Industrial and Commercial to Part Number table.
			Corrected I/O counts in the part number tables for 100/144 TQFP and 208 PQFP packages to match Table 1-1 on page 1.
November 2004	01.3	Introduction	Changed DDR333 (166MHz) to DDR400 (200MHz)
			Added “RSDS” offering to the Features list: Flexible I/O Buffer
		Architecture	Added information about Secondary Clock Sources
			Added information about DCS
			Added a section on “Recommended Power-up Sequence”
			Updated Figure 2-24 “DQS Routing”
			Added DSP Block performance numbers to Table 2-11
			Added another row for RSDS in Table 2-13 and Table 2-14
		DC & Switching Characteristics	Updated new timing numbers
			Added numbers to derating table
			Added DC conditions to RSDS table
			Changed LVDS Max. V_{CCIO} to 2.625
			Added a row for RSDS in “Operating Condition” table
			Updated standby and initialization current table
			Added figure 3-12: sysConfig SPI port sequence
			Added DDR Timing Table and DDR Timings Figure 3-6
		Pinout Information	Added LFECP/EC6 to Pin Information
			Added LFECP/EC6 to Power Supply and NC Connections
			Added LFECP/EC6 144 TQFP Logic Signal Connections
			Added LFECP/EC6 208 PQFP Logic Signal Connections
			Added LFECP/EC6 256 fpBGA Logic Signal Connections
			Added LFECP/EC6 484 fpBGA Logic Signal Connections
		Ordering Information	Added 33K Logic Capacity Device in Part Number Description section.
			Added Part Number table for Commercial EC33.
			Added Part Number table for Commercial ECP33.
			Added Part Number table for Industrial EC33.
			Added Part Number table for Industrial ECP33.

Date	Version	Section	Change Summary
December 2004	01.4	Architecture	Updated Hot Socketing Recommended Power Up Sequence section.
		Pinout Information	Added LFEC1, LFEC3, LFECP/EC10, LFECP/EC15 to Pin Information
			Added LFEC1, LFEC3, LFECP/EC10, LFECP/EC15 to Power Supply and NC Connections
			Added LFEC1 and LFEC3 100 TQFP Pinout
			Added LFEC1 and LFEC3 144 TQFP Pinout
			Added LFEC1, LFEC3 and LFECP/EC10 208 PQFP Pinout
			Added LFEC3, LFECP/EC10 and LFECP/EC15 256 fpBGA Pinout
			Added LFECP/EC10 and LFECP/EC15 484 fpBGA Pinout
		Ordering Information	Added Lead-Free Package Designators
			Added Lead-Free Ordering Part Numbers
		Supplemental Information	Updated list of technical notes.
April 2005	01.5	Architecture	EBR memory support section has been updated with clarification.
			Updated sysIO buffer pair section.
		DC & Switching Characteristics	Hot Socketing Specification has been updated.
			DC Electrical Characteristics table (I_{IL}, I_{IH}) has been updated.
			Supply Current (Standby) table has been updated.
			Initialization Supply Current table has been updated.
			External Switching Characteristics section has been updated.
			Removed t_{RSTW} spec. from PLL Parameter table.
			t_{RST} specifications have been updated.
			sysCONFIG Port Timing Specifications (t_{BSCL}, t_{IODISS}, t_{PRGMRJ}) have been updated.
		Pinout Information	Added LFECP/EC33 Pinout Information
			Pin Information Summary table has been updated.
			Power Supply and NC Connection table has been updated.
			484-fpBGA logic connection has been updated (Ball # J6, J17, P6 and P17 for ECP/EC33 are now called VCCPLL).
			672-fpBGA logic connection has been updated (Ball # K19, L8, U19, U8 for ECP/EC33 are now called VCCPLL).
May 2005	01.6	Introduction	ECP/EC33 EBR SRAM Bits and Blocks have been updated to 498K and 54 respectively.
		Architecture	Table 2-10 has been updated (ECP/EC33 EBR SRAM Bits and Blocks have been updated to 498K and 54 respectively.)
			Recommended Power Up Sequence section has been removed.
		DC & Switching Characteristics	Supply Current (Standby) table has been updated.
			Initialization Supply Current table has been updated.
			Vos test condition has been updated to (VOP+VOM)/2.
			Register-to-Register performance table has been updated (rev. G 0.27).
			External switching characteristics have been updated (rev. G 0.27).
			Internal timing parameters have been updated (rev. G 0.27).
			Timing adders have been updated (rev. G 0.27).
			sysCONFIG port timing specifications have been updated.
		Pinout Information	Pin Information Summary table has been updated.
			Power Supply and NC Connection table has been updated.
		Ordering Information	OPN list has been updated.